ABSTRACT

HEAT SPREADER ANCHORING & GROUNDING METHOD & THERMALLY ENHANCED PBGA PACKAGE USING THE SAME

A method and assembly are provided for anchoring the heat spreader of a PBGA package to the substrate thereof as part of the PBGA package. These anchor features are provided over the surface of the substrate of the PBGA package. The anchor features align with openings created in the heat spreader stand-off, thus allowing for quick and reliable positioning and anchoring of the heat spreader over the surface of the substrate of the package. (Fig. 3)